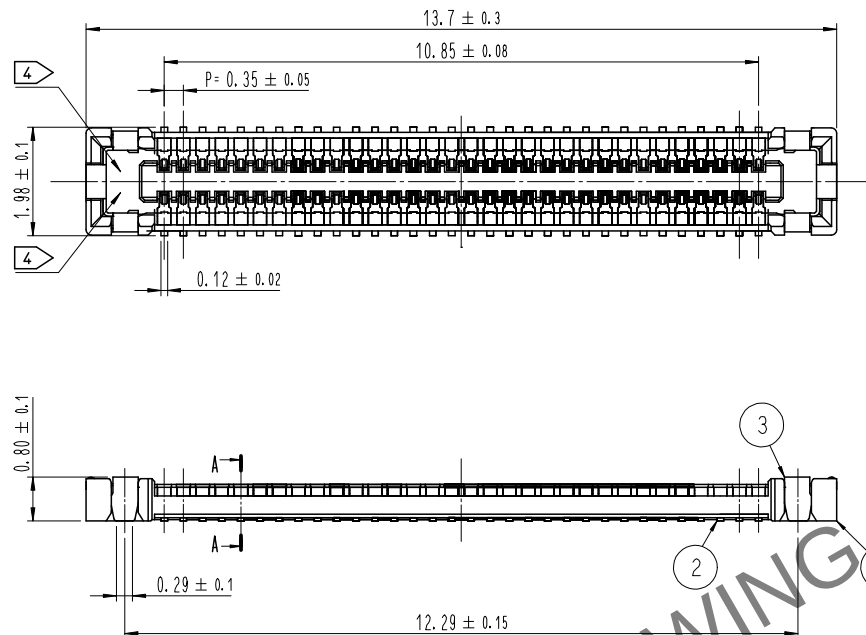
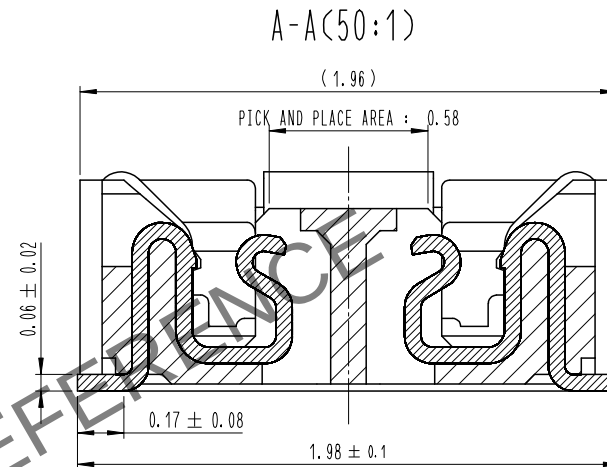


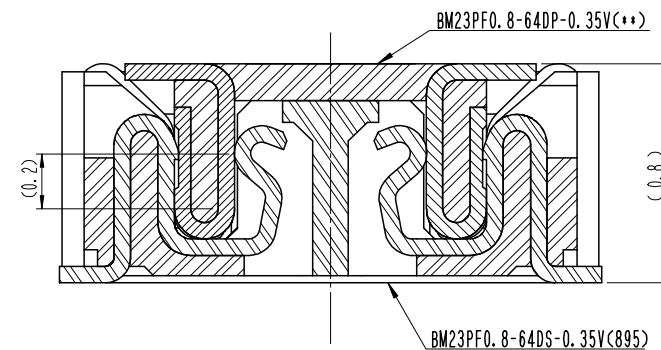


- NOTE
- 1. ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX.
 - 2. CONTACT PLATING SPECIFICATIONS.
CONTACT AREA : GOLD $0.05 \mu\text{m}$ MIN.
SMT LEAD : GOLD $0.05 \mu\text{m}$ MIN.
UNDERPLATING : NICKEL $1 \mu\text{m}$ MIN.
(SURFACE : SEALING)
 - 3. METAL FITTING PLATING SPECIFICATIONS.
SMT LEAD : GOLD $0.05 \mu\text{m}$ MIN.
UNDERPLATING : NICKEL $1 \mu\text{m}$ MIN.
(SURFACE : SEALING)
 - 4. HRS MARK AND CAV NO. IS INDICATED IN APPROX POSITION SHOWN.

△數 COUNT	訂正事項 DESCRIPTION OF REVISIONS	擔當 B Y	檢圖 CHKD	年月日 DATE	△數 COUNT	訂正事項 DESCRIPTION OF REVISIONS	擔當 B Y	檢圖 CHKD	年月日 DATE
△					△				
△					△				
△					△				

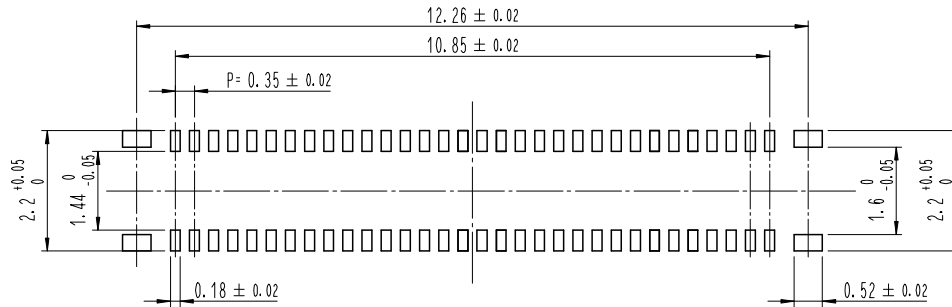


ENGAGEMENT FIGURE (50:1)



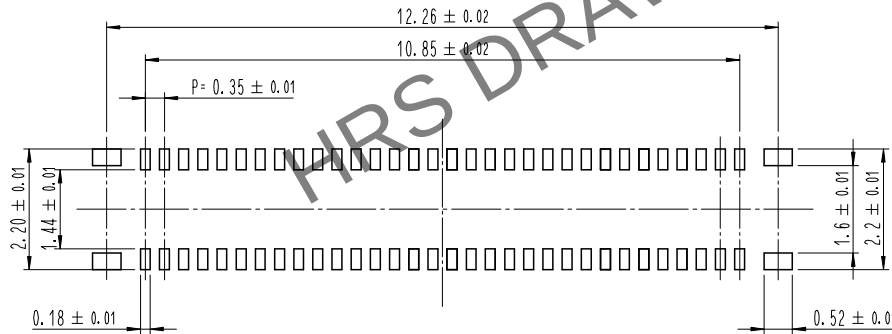
4	PS	CLEAR (EMBOSSED CARRIER TAPE)							
3	COPPER ALLOY	3		7	PS	CLEAR (REINFORCEMENT COLLAR)			
2	COPPER ALLOY	2		6	PS	BLACK (PLASTIC REEL)			
1	LCP	UL94 V-0, BLACK		5	POLYESTER	CLEAR (COVER TAPE)			
NO.	MATERIAL	FINISH , REMARKS		NO.	MATERIAL	FINISH , REMARKS			
REMARKS					DRAWN	DESIGNED	CHECKED	APPROVED	RELEASED
					W. J. LEE	W. J. LEE	H. W. JO	H. W. JO	20. 04. 21
					20. 04. 21	20. 04. 21	20. 04. 21	20. 04. 21	
CODE NO. (OLD)			DRAWING NO.		PART NO.				
		SCALE	EDC3-632893-95		BM23PF0. 8-64DS-0. 35V(895)				
		10:1							
		UNITS	HIROSE KOREA CO., LTD.		CODE NO		CL 6644-0105-2-895		1/3

6 RECOMMENDED PCB LAYOUT

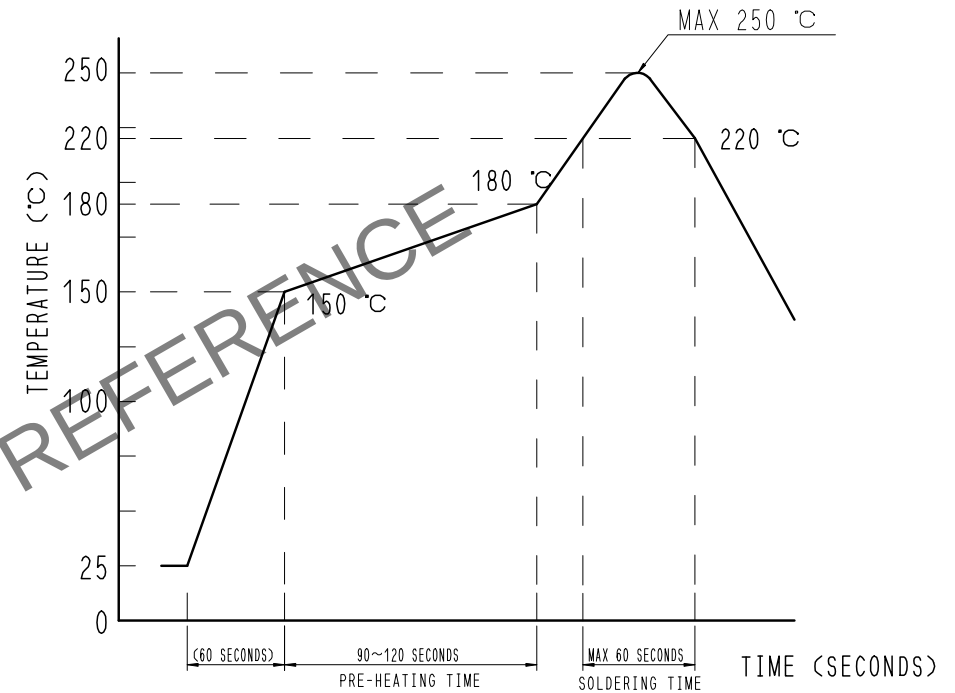


RECOMMENDED METAL MASK DIMENSIONS

METAL MASK THICKNESS : $100 \mu\text{m}$



5 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



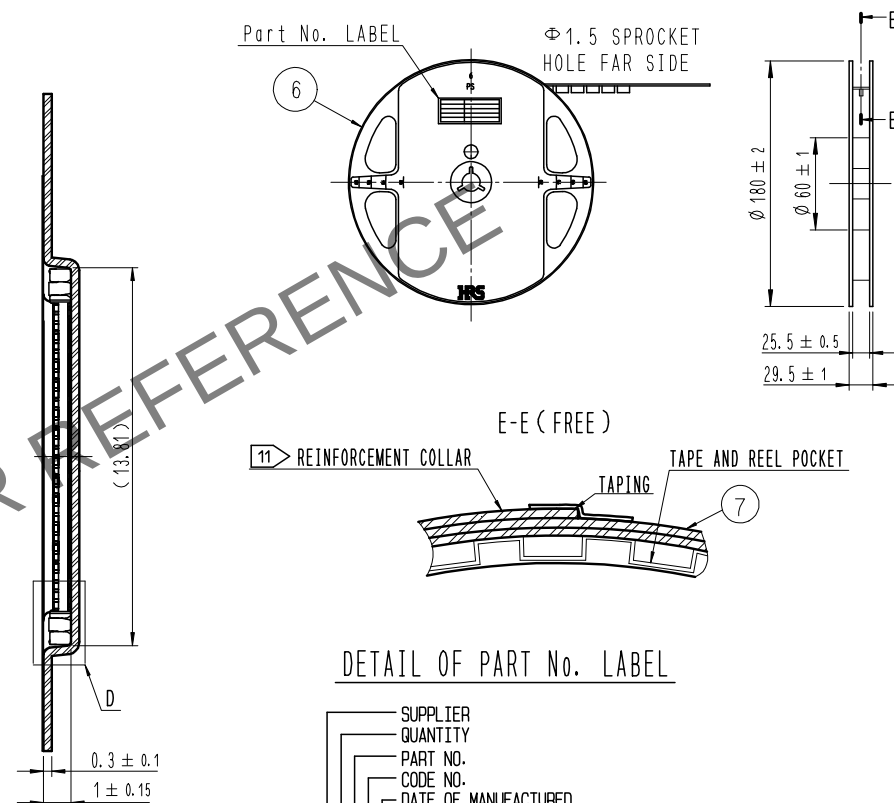
REFLOW METHOD: N_2 REFLOW
NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.

- 1) REFLOW TIME
DURATION ABOVE 220°C : 60 SEC MAX.
(PEAK TEMPERATURE: 250°C MAX)
- 2) PRE-HEAT TIME
PRE-HEAT TEMPERATURE(MIN): 150°C
PRE-HEAT TEMPERATURE(MAX): 180°C
PRE-HEAT TIME: 90~120 SEC.

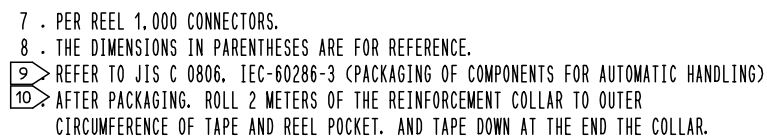
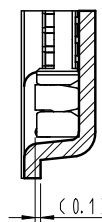
- 5 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE. THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.
- 6 PLEASE CONTACT US IN CASE YOU WILL MAKE DIFFERENT SETTINGS FROM OUR RECOMMENDATION.

	DRAWING NO.	EDC3-632893-95	PART NO.	BM23PF0.8-64DS-0.35V(895)
	SCALE	10:1	CODE NO.	CL 6644-0105-2-895
UNITS	HIROSE KOREA CO., LTD.			2/3

STYLE AND DIMENTION OF REEL (FREE)



D (10:1)



	DRAWING NO.	EDC3-632893-95	PART NO.	BM23PF0.8-64DS-0.35V(895)	
	SCALE 10:1 UNITS mm	 HIROSE KOREA CO., LTD.		CODE NO	CL 6644-0105-2-895